

Materials Declaration

Package	SOIC-EP
Body Size	150 mils
LeadCount	8
Option	Pb-Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SiO2 Filler	87.00	3.99 E-02	504920
Epoxy resin	5.90	2.68 E-03	33950
Sb2O3	4.10	1.90 E-03	24084
Phenol Resin	3.00	1.38 E-03	17405

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.88 E-02	894302
Fe	2.35	6.94 E-04	8778
Zn	0.12	3.50 E-05	443
P	0.03	9.00 E-06	114

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100.0	4.29 E-04	5428

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100.0	1.80 E-03	22717

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	2.30 E-04	2909

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.0	6.48 E-04	8197

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70.0	3.74 E-04	4731
Resin	21.0	1.12 E-04	1417
Metal Oxide	3.0	1.60 E-05	202
Amine	3.0	1.60 E-05	202
Gamma Butyrolactone	3.0	1.60 E-05	202

Molding Compound		
Item	PPM	Method
Pb	None Detected	US EPA 3050B. Analysis was performed by ICP-AES
Cd	None Detected	US EPA 3050B. Analysis was performed by ICP-AES
Hg	None Detected	US EPA 3052. Analysis was performed by ICP-AES
Cr+6	None Detected	US EPA 3060A. Analysis was performed by UV-VIS
PBB	None Detected	US EPA 3450C. Analysis was performed by GC/MS
PBDE	None Detected	US EPA 3450C. Analysis was performed by GC/MS

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	US EPA 3050B. Analysis was performed by ICP-AES
Cd	None Detected	EN 1122 Method B. Analysis was performed by ICP-AES
Hg	None Detected	US EPA 3052. Analysis was performed by ICP-AES
Cr+6	None Detected	EPA 3060A & 7196A
PBB	None Detected	US EPA 3540 or 3550. Analysis by HPLC/DAD, LC/MS or GC/MS
PBDE	None Detected	US EPA 3540 or 3550. Analysis by HPLC/DAD, LC/MS or GC/MS

Package Totals	
Weight (g)	PPM
7.91 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability for any inaccuracy of such information.



ADI Proprietary



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LeadCount	8
Option	Sn/Pb

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SiO2 Filler	97.00	3.99 E-02	604920
Epoxy resin	5.90	2.68 E-03	33950
Sb2O3	4.10	1.90 E-03	24084
Phenol Resin	3.00	1.38 E-03	17405

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.88 E-02	364302
Fe	2.35	6.94 E-04	8778
Zn	0.12	3.50 E-05	443
P	0.03	8.00 E-06	114

Internal Leadframe Plating		
% of Plating	Weight (g)	PPM
Ag	4.29 E-04	5426

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85.0	1.53 E-03	19310
Pb	15.0	2.69 E-04	3408

Bond Wires			
% of Wire	Weight (g)	PPM	
Au	99.99	2.30 E-04	2309

Chip			
% of Chip	Weight (g)	PPM	
Si	100.0	6.48 E-04	8197

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70.0	3.74 E-04	4731
Resin	21.0	1.12 E-04	1417
Metal Oxide	3.0	1.60 E-05	202
Armine	3.0	1.60 E-05	202
Gamma Butyrolactone	3.0	1.60 E-05	202

Package Totals	
Weight (g)	PPM
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Hg	None Detected	US EPA 3052. Analysis was performed by ICP-AES
Cr+6	None Detected	US EPA 3060A. Analysis was performed by UV-VIS
PBB	None Detected	US EPA 3450C. Analysis was performed by GC/MS
PBDE	None Detected	US EPA 3450C. Analysis was performed by GC/MS

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	US EPA 3050B. Analysis was performed by ICP-AES
Cd	None Detected	EN 1122 Method B. Analysis was performed by ICP-AES
Hg	None Detected	US EPA 3052. Analysis was performed by ICP-AES
Cr+6	None Detected	EPA 3060A & 7196A
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